

WHAT IS CLAIMED IS:

1. A method of delivering a target object to be
processed onto a transfer mechanism for allowing said
transfer mechanism to take the target object from a
5 table, comprising the steps of:

inclining the target object by making one end of
the target object disposed on a table and having a
predetermined processing applied thereto higher than
the other end; and

10 allowing the transfer mechanism to hold said
inclined target object.

2. The delivering method according to claim 1,
wherein a part of the target object is allowed to rise
from the surface of the table so as to provide air
15 between the target object and the table in the step of
inclining the target object.

3. The delivering method according to claim 1,
wherein the step of inclining the target object
comprises the sub-steps of:

20 making one end of the target object higher than
the other end so as to allow the target object to have
a predetermined inclination; and

moving upward the target object to a predetermined
height while maintaining the inclination.

25 4. The delivering method according to claim 1,
wherein the step of inclining the target object
comprises the sub-steps of:

moving upward the target object to a predetermined height in parallel to the surface of the table; and

making one end of the target object higher than the other end so as to incline the target object.

5 5. The delivering method according to claim 1, wherein the target object is inclined such that the other end of the target object is brought out of contact with the table in the step of inclining the target object.

10 6. The delivering method according to claim 1, wherein the target object is a semiconductor wafer, said predetermined processing is an inspection of the electrical characteristics of the integrated circuit formed on the semiconductor wafer, and said transfer
15 mechanism is a pincette for transferring the semiconductor wafer.

 7. The delivering method according to claim 6, wherein the step of inclining the target object of the semiconductor wafer is performed by controlling the
20 height to which each of a plurality of lift pins for supporting the semiconductor wafer, which are arranged in an upper portion of the table, is moved.

 8. The delivering method according to claim 7, wherein the step of inclining the target object
25 comprises the sub-steps of:

moving upward at least one lift pin at a predetermined speed so as to cause a part of the target

object to rise from the surface of the table, thereby introducing air into the clearance between the target object and the table; and

moving upward each of the lift pins at a speed
5 higher than said predetermined speed so as to move upward the target object.

9. A table mechanism, comprising a table for performing the delivery of the target object to and from a transfer mechanism of the target object, and a
10 plurality of lift pins for causing the target object on said table to rise from the table surface so as to support the target object, wherein at least one lift pin positioned on the side of the transfer mechanism is moved higher than the other lift pins such that the
15 target object is supported by said lift pins in an inclined fashion.

10. A table mechanism for receiving the target object transferred by a transfer mechanism, for applying a predetermined processing to the received
20 target object, and for delivering the processed target object onto the transfer mechanism, comprising:

a table having the target object disposed thereon and provided with a plurality of lift pins in an upper portion thereof, said lift pins being moved upward from
25 within the table onto the outside of the table when receiving the target object transferred by said transfer mechanism and when delivering the processed

target object onto said transfer mechanism;

a driving mechanism for vertically moving said plural lift pins; and

5 a control mechanism for controlling said driving mechanism, said control mechanism moving upward at least one of said lift pins to a position higher than the positions to which the other lift pins are moved upward, when the processed target object is delivered from the table onto the transfer mechanism, so as to
10 incline the target object supported by said plural lift pins.

11. The table mechanism according to claim 10, wherein the control of the driving mechanism performed by the control mechanism of the table mechanism is
15 performed such that, when the processed target object is delivered onto the transfer mechanism, at least one of the lift pins is moved upward at a predetermined speed so as to cause a part of the target object to float from the surface of the table, thereby
20 introducing air into the clearance between the target object and the table, followed by moving upward the plural lift pins at a speed higher than said predetermined speed.

12. The table mechanism according to claim 10,
25 wherein the control of the driving mechanism performed by the control mechanism of the table mechanism is performed such that the target object is moved upward

in parallel to the surface of the table to reach a predetermined height, and that one end of the target object is made higher than the other end so as to incline the target object.

5 13. The table mechanism according to claim 10,
wherein the control of the driving mechanism performed
by the control mechanism of the table mechanism is
performed such that one end of the target object on the
10 other end so as to impart a predetermined inclination
to the target object, and the target object is moved
upward to a predetermined height while maintaining the
inclined state.

15 14. The table mechanism according to claim 10,
wherein the control of the driving mechanism performed
by the control mechanism of the table mechanism is
performed such that the target object is inclined by
making higher one end of the target object on the side
of the driving mechanism, and that the degree of
20 inclination is controlled such that the other end of
target object is brought out of contact with the table.

25 15. The table mechanism according to claim 10,
wherein the target object is a target object to be
inspected, and said predetermined processing is the
inspection of the electrical characteristics of the
target object.

16. The table mechanism according to claim 10,

wherein the target object to be processed is a semiconductor wafer, said predetermined processing is an inspection of the electrical characteristics of the integrated circuit formed on a semiconductor wafer, and
5 said transfer mechanism is a pincette for transferring the semiconductor wafer.